



Material Content Data Sheet



Sales Product Name	TLD1310EL			Issued	1. August 2018			
MA#	MA001179050							
Package	PG-SSOP-14-5			Weight*	82.76 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.376	1.66	1.66	16632	16632
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		416	
	non noble metal	iron	7439-89-6	0.689	0.83		8326	
wire	non noble metal	copper	7440-50-8	27.978	33.81	34.69	338076	346922
	non noble metal	copper	7440-50-8	0.069	0.08	0.08	831	831
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1217
encapsulation	plastics	epoxy resin	-	4.634	5.60		56000	
	inorganic material	silicondioxide	60676-86-0	45.638	55.15	60.87	551483	608700
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11795	11795
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9276	9276
glue	plastics	epoxy resin	-	0.121	0.15		1461	
	noble metal	silver	7440-22-4	0.363	0.44	0.59	4383	5844
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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